OP27A, OP27C LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL AMPLIFIERS

SLOS100E - FEBRUARY 1989 - REVISED FEBRUARY 2010

 Replacements for ADI, PMI and LTC OP27 Series

Features of OP27A and OP27C:

- Maximum Equivalent Input Noise Voltage:
 3.8 nV/√Hz at 1 kHz
 5.5 nV/√Hz at 10 kHz
- Very Low Peak-to-Peak Noise Voltage at 0.1 Hz to 10 Hz ... 80 nV Typ
- Low Input Offset Voltage
 OP27A . . . 25 μV Max
 OP27C . . . 100 μV Max
- High Voltage Amplification
 OP27A . . . 1 V/μV Min
 OP27C . . . 0.7 V/μV Min

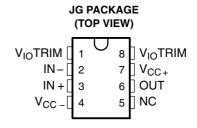
description

The OP27 operational amplifiers combine outstanding noise performance with excellent precision and high-speed specifications. The wideband noise is only 3 nV/ $\sqrt{\text{Hz}}$ and with the 1/f noise corner at 2.7 Hz, low noise is maintained for all low-frequency applications.

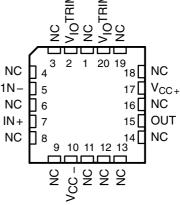
The outstanding characteristics of the OP27 make these devices excellent choices for low-noise amplifier applications requiring precision performance and reliability.

The OP27 series is compensated for unity gain.

The OP27A and OP27C are characterized for operation over the full military temperature range of -55°C to 125°C.

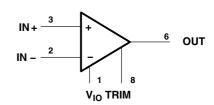






NC - No internal connection

symbol



Pin numbers are for the JG packages.

AVAILABLE OPTIONS

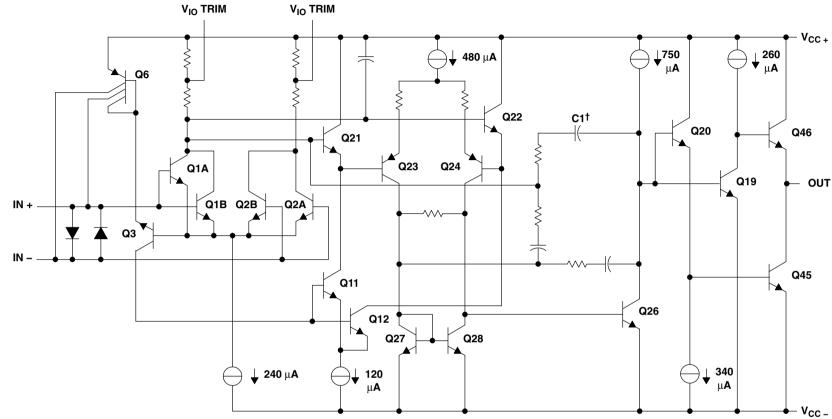
	V	CTA DI E	PACKAGE				
T _A	V _{IO} max AT 25°C	STABLE GAIN	CERAMIC DIP (JG)	CHIP CARRIER (FK)			
-55°C to 125°C	25 μV	1	OP27AJG	OP27AFK			
-55 0 10 125 0	100 μV	1	OP27CJG				



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.



SLOS100E - FEBRUARY 1989 - REVISED FEBRUARY 2010



[†] C1 = 120 pF for OP27



OP27A, OP27C LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL-AMPLIFIER

SLOS100E - FEBRUARY 1989 - REVISED FEBRUARY 2010

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V _{CC+} (see Note 1)	22 V
Supply voltage, V _{CC} (see Note 1)	22 V
Input voltage, V _I	V _{CC±}
Duration of output short circuit	unlimited
Differential input current (see Note 2)	±25 mA
Continuous power dissipation	. See Dissipation Rating Table
Operating free-air temperature range: OP27A, OP27C	–55°C to 125°C
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: JG or FK pa	ckage 300°C

NOTES: 1. All voltage values are with respect to the midpoint between V_{CC-} and V_{CC-} unless otherwise noted.

The inputs are protected by back-to-back diodes. Current-limiting resistors are not used in order to achieve low noise. Excessive
input current will flow if a differential input voltage in excess of approximately ±0.7 V is applied between the inputs unless some
limiting resistance is used.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING	
JG	1050 mW	8.4 mW/°C	546 mW	210 mW	
FK	1375 mW	11.0 mW/°C	715 mW	275 mW	

OP27A, OP27C LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL-AMPLIFIER

SLOS100E - FEBRUARY 1989 - REVISED FEBRUARY 2010

recommended operating conditions

			OP27A			OP27C		
		MIN	NOM	MAX	MIN	NOM	MAX	UNIT
Supply voltage, V _{CC+}	4	15	22	4	15	22	V	
Supply voltage, V _{CC} _		-4	-15	-22	-4	-15	-22	V
O	$V_{CC\pm} = \pm 15 \text{ V}, T_A = 25^{\circ}\text{C}$	± 11			±11			.,
Common-mode input voltage, V _{IC}	$V_{CC\pm} = \pm 15 \text{ V}, T_A = -55^{\circ}\text{C to } 125^{\circ}\text{C}$	±10.3			±10.2			V
Operating free-air temperature, TA	-55		125	-55		125	°C	

electrical characteristics at specified free-air temperature, $V_{CC\pm}$ = ± 15 V (unless otherwise noted)

200					OP27A				OP27C		
	PARAMETER	TEST CO	ONDITIONS	T _A †	MIN	TYP	MAX	MIN	TYP	MAX	UNIT
.,	lowed offeet valtage	$V_{O} = 0$,	V _{IC} = 0	25°C		10	25		30	100	
V_{IO}	Input offset voltage	$R_S = 50 \Omega$,	See Note 3	Full range			60			300	μV
α_{VIO}	Average temperature coefficient of input offset voltage			Full range		0.2	0.6		0.4	1.8	μV/°C
	Long-term drift of input offset voltage	See Note 4				0.2	1		0.4	2	μV/mo
,	Input offset current	V _O = 0,	V _{IC} = 0	25°C		7	35		12	75	nA
I _{IO}	input onset current	v _O = 0,	v _{IC} = 0	Full range			50			135	IIA
l	Input bias current	V _O = 0,	V 0	25°C		±10	±40		±15	±80	nA
I _{IB}	input bias current	v _O = 0,	v _{IC} = 0	Full range			±60			±150	IIA
Common-mode input				25°C	11 to –11			11 to –11			V
VICH	voltage range			Full range	10.3 to -10.3			10.5 to -10.5			•
		$R_L \geq 2~k\Omega$			±12	±13.8		±11.5	±13.5		
V_{OM}	Peak output voltage swing	$R_L \ge 0.6 \text{ k}\Omega$			±10	±11.5		±10	±11.5		V
		$R_L \geq 2~k\Omega$		Full range	±11.5			10.5			
			$V_O = \pm 10 \text{ V}$		1000	1800		700	1500		
	Large-signal differential		$V_O = \pm 10 \text{ V}$		800	1500			1500		
A _{VD}	voltage amplification	$R_L \ge 0.6 \text{ k}\Omega$ $V_{CC\pm} = \pm 4$	$V_{O} = \pm 1 V,$		250	700		200	500		V/mV
		$R_L \ge 2 k\Omega$,	$V_O = \pm 10 \text{ V}$	Full range	600			300			
r _{i(CM)}	Common-mode input resistance					3			2		GΩ
ro	Output resistance	$V_O = 0$,	I _O = 0	25°C		70			70		Ω
CMRR	Common-mode rejection	V _{IC} = ±11 V		25°C	114	126		100	120		dB
CIVINK	ratio	$V_{IC} = \pm 10 \text{ V}$	1	Full range	110			94			uБ
kova	Supply voltage rejection	$V_{CC\pm} = \pm 4 \text{ V to } \pm 18 \text{ V}$		25°C	100	120		94	118		dB
k _{SVR}	ratio	$V_{CC\pm} = \pm 4.5$	5 V to ±18 V	Full range	96			86			מט

 $^{^{\}dagger}$ Full range is – 55°C to 125°C.

NOTES: 3. Input offset voltage measurements are performed by automatic test equipment approximately 0.5 seconds after applying power.

^{4.} Long-term drift of input offset voltage refers to the average trend line of offset voltage versus time over extended periods after the first 30 days of operation. Excluding the initial hour of operation, changes in V_{IO} during the first 30 days are typically 2.5 μV (see Figure 3).



OP27A, OP27C LOW-NOISE HIGH-SPEED PRECISION OPERATIONAL-AMPLIFIER

SLOS100E - FEBRUARY 1989 - REVISED FEBRUARY 2010

OP27 operating characteristics, V_{CC^\pm} = ± 15 V, T_A = $25^{\circ}C$

DADAMETER		TEST CONDITIONS		OP27A			OP27C			
	PARAMETER	TEST CONDITIONS		MIN	TYP	MAX	MIN	TYP	MAX	UNIT
SR	Slew rate	$A_{VD} \geq 1, \\$	$R_L \ge 2 \ k\Omega$	1.7	2.8		1.7	2.8		V/µs
V _{N(PP)}	Peak-to-peak equivalent input noise voltage	f = 0.1 Hz to 10 Hz, See Figure 26	$R_S = 20 \Omega$,		0.225	0.375		0.225	0.375	μV
V	Facility along the set water water	f = 10 Hz,	$R_S = 20 \Omega$		3.5	8		3.8	8	VII /III
V _n	Equivalent input noise voltage	f = 1 kHz,	$R_S = 20 \Omega$		3	4		3.2	4	nV/√Hz
	Facilitation of males assument	f = 10 Hz,	See Figure 27		5	25		5	25	- A /-/III=
'n	Equivalent input noise current	f = 1 kHz,	See Figure 27		0.7	2.5		0.7	2.5	pA/√ Hz
	Gain-bandwidth product	f = 100 kHz		5	8		5	8		MHz

Table of Graphs

			FIGURE
V _{IO}	Input offset voltage	vs Temperature	1
ΔV_{IO}	Change in input offset voltage	vs Time after power on vs Time (long-term drift)	2 3
I _{IO}	Input offset current	vs Temperature	4
I _{IB}	Input bias current	vs Temperature	5
V _{ICR}	Common-mode input voltage range	vs Supply voltage	6
V _{OM}	Maximum peak output voltage	vs Load resistance	7
V _{O(PP)}	Maximum peak-to-peak output voltage	vs Frequency	8
A _{VD}	Differential voltage amplification	vs Supply voltage vs Load resistance vs Frequency	9 10 11, 12
CMRR	Common-mode rejection ratio	vs Frequency	13
k _{SVR}	Supply voltage rejection ratio	vs Frequency	14
SR	Slew rate	vs Temperature	15
φ _m	Phase margin	vs Temperature	16
ф	Phase shift	vs Frequency	11
V _n	Equivalent input noise voltage	vs Bandwidth vs Source resistance vs Supply voltage vs Temperature vs Frequency	17 18 19 20 21
	Gain-bandwidth product	vs Temperature	16
los	Short-circuit output current	vs Time	22
Icc	Supply current	vs Supply voltage	23
	Pulse response	Small signal Large signal	24 25

REPRESENTATIVE INDIVIDUAL UNITS FREE-AIR TEMPERATURE 100 $V_{CC\pm} = \pm 15 \text{ V}$ 80 OP27C 60 V_{IO} – Input Offset Voltage – μ V OP27A 40 OP27A 20 0 - 20 - 40 OP27C - 60 - 80

- 100 L - 50

- 25

INPUT OFFSET VOLTAGE OF

WARM-UP CHANGE IN INPUT OFFSET VOLTAGE VS ELAPSED TIME

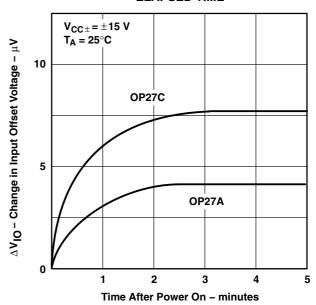


Figure 1

T_A - Free-Air Temperature - °C

Figure 2

LONG-TERM DRIFT OF INPUT OFFSET VOLTAGE OF REPRESENTATIVE INDIVIDUAL UNITS

100

125

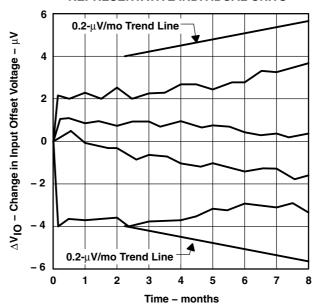
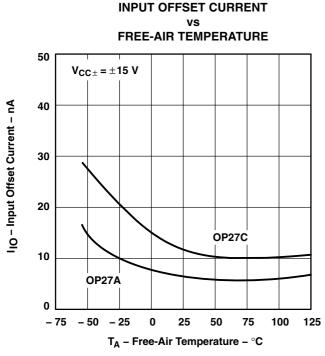


Figure 3



IB - Input Bias Current - nA $\pm\,20$ OP27C ± 10 OP27A - 75 - 50 - 25 25 50 75 T_A – Free-Air Temperature – $^{\circ}C$

 $\pm\,$ 50

 \pm 40

 $\pm\,$ 30

 $V_{CC\pm} = \pm 15 \text{ V}$

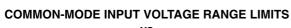
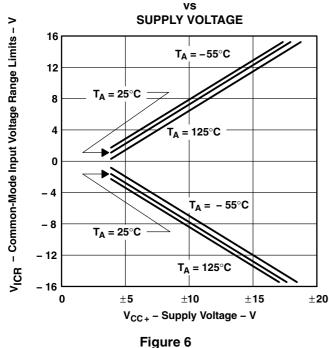


Figure 4



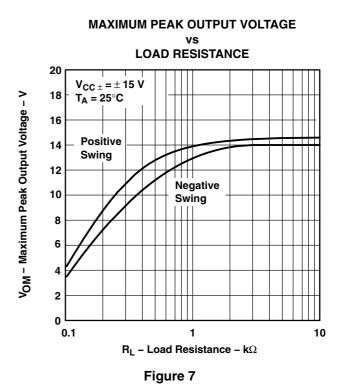


Figure 5

INPUT BIAS CURRENT

FREE-AIR TEMPERATURE

100

125

OP27 MAXIMUM PEAK-TO-PEAK OUTPUT VOLTAGE

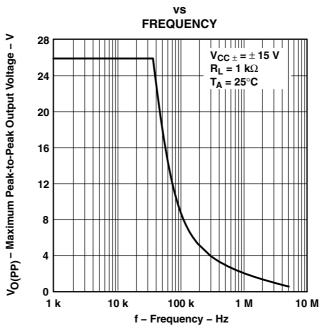


Figure 8.

OP27A LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION VS

TOTAL SUPPLY VOLTAGE

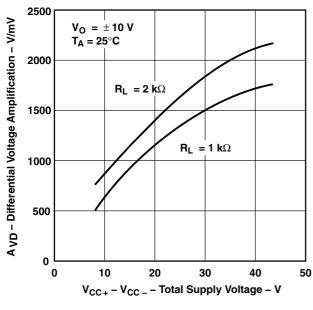


Figure 9

OP27A LARGE-SIGNAL DIFFERENTIAL VOLTAGE AMPLIFICATION

vs LOAD RESISTANCE

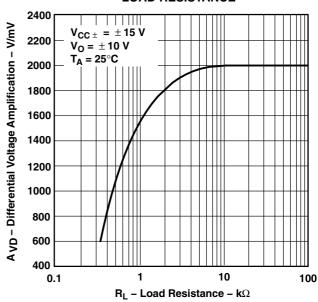


Figure 10



OP27 LARGE-SIGNAL DIFFERENTIAL **VOLTAGE AMPLIFICATION AND PHASE SHIFT**

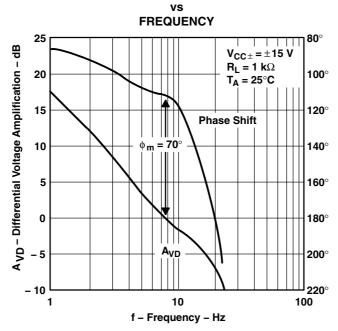


Figure 11.

OP27A LARGE-SIGNAL **DIFFERENTIAL VOLTAGE AMPLIFICATION**

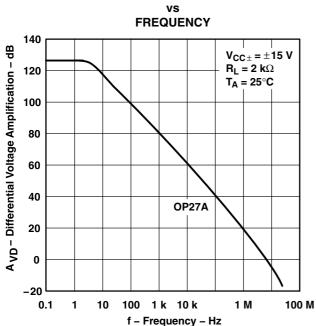


Figure 12

OP27A **COMMON-MODE REJECTION RATIO** VS

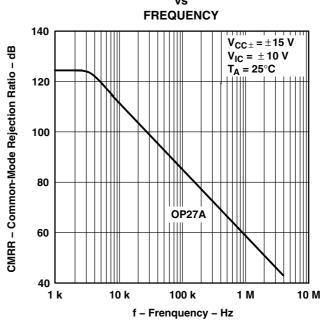


Figure 13

SUPPLY VOLTAGE REJECTION RATIO FREQUENCY 160 $V_{CC\pm} = \pm 4 \text{ V to } \pm 18 \text{ V}$ kSVR - Supply Voltage Rejection Ratio - dB $T_A = 25^{\circ}C$ 140 120 100 Negative Supply 80 60 40 **Positive** Supply 20 0 10 1k 10k 100k 1M 10M 100M 100 f - Frequency - Hz

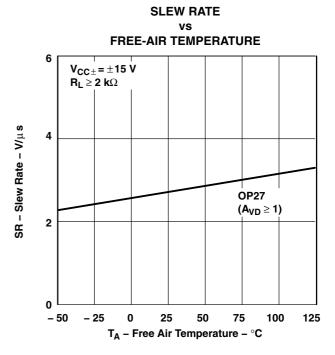


Figure 14

Figure 15

OP27 PHASE MARGIN AND GAIN-BANDWIDTH PRODUCT

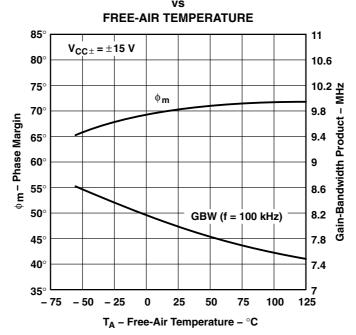


Figure 16.

EQUIVALENT INPUT NOISE VOLTAGE vs BANDWIDTH

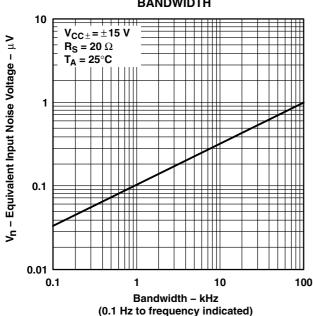


Figure 17 OP27A EQUIVALENT INPUT NOISE VOLTAGE VS TOTAL SUPPLY VOLTAGE

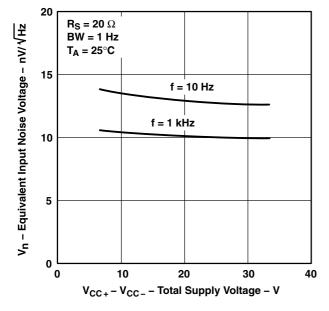


Figure 19

TOTAL EQUIVALENT INPUT NOISE VOLTAGE

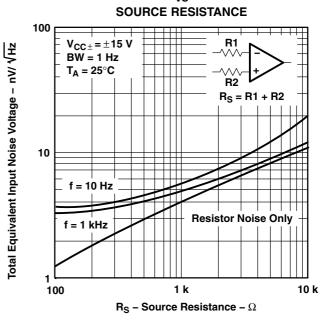


Figure 18

OP27A

EQUIVALENT INPUT NOISE VOLTAGE

vs

FREE-AIR TEMPERATURE

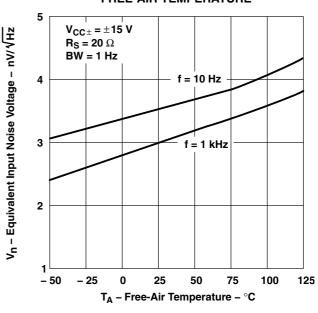


Figure 20

OP27A EQUIVALENT INPUT NOISE VOLTAGE vs

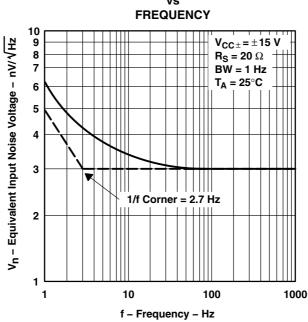


Figure 21

SHORT-CIRCUIT OUTPUT CURRENT

vs **ELAPSED TIME** 60 $V_{CC\pm}$ = \pm 15 V $T_A = 25^{\circ}C$ IOS - Short-Circuit Output Current - mA 50 los-40 30 los+ 20 10 3 4 0 5 t - Time - minutes

Figure 22

SUPPLY CURRENT vs

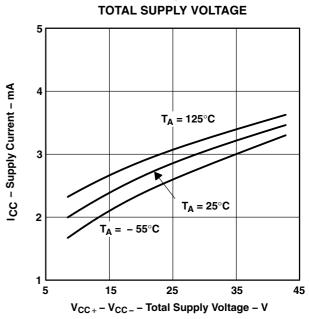
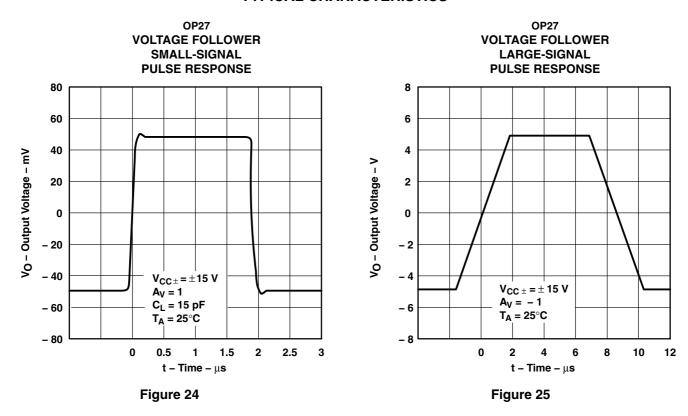


Figure 23

SLOS100E - FEBRUARY 1989 - REVISED FEBRUARY 2010

TYPICAL CHARACTERISTICS



APPLICATION INFORMATION

general

The OP27 series devices can be inserted directly onto OP07, OP05, μ A725, and SE5534 sockets with or without removing external compensation or nulling components. In addition, the OP27 can be fitted to μ A741 sockets by removing or modifying external nulling components.

noise testing

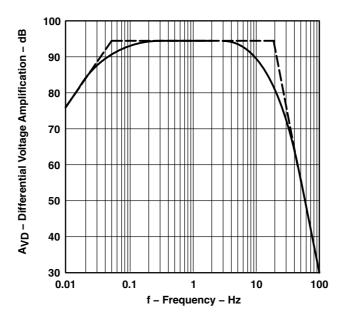
Figure 26 shows a test circuit for 0.1-Hz to 10-Hz peak-to-peak noise measurement of the OP27. The frequency response of this noise tester indicates that the 0.1-Hz corner is defined by only one zero. Because the time limit acts as an additional zero to eliminate noise contributions from the frequency band below 0.1 Hz, the test time to measure 0.1-Hz to 10-Hz noise should not exceed 10 seconds.

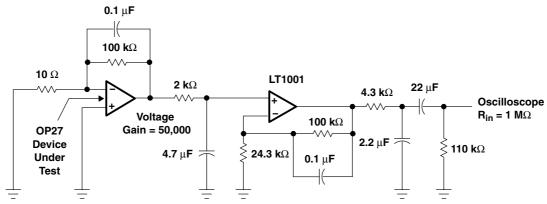
Measuring the typical 80-nV peak-to-peak noise performance of the OP27 requires the following special test precautions:



noise testing (continued)

- 1. The device should be warmed up for at least five minutes. As the operational amplifier warms up, the offset voltage typically changes 4 μ V due to the chip temperature increasing from 10°C to 20°C starting from the moment the power supplies are turned on. In the 10-s measurement interval, these temperature-induced effects can easily exceed tens of nanovolts.
- 2. For similar reasons, the device should be well shielded from air currents to eliminate the possibility of thermoelectric effects in excess of a few nanovolts, which would invalidate the measurements.
- 3. Sudden motion in the vicinity of the device should be avoided, as it produces a feedthrough effect that increases observed noise.





NOTE: All capacitor values are for nonpolarized capacitors only.

Figure 26. 0.1-Hz to 10-Hz Peak-to-Peak Noise Test Circuit and Frequency Response



noise testing (continued)

When measuring noise on a large number of units, a noise-voltage density test is recommended. A 10-Hz noise-voltage density measurement correlates well with a 0.1-Hz to 10-Hz peak-to-peak noise reading since both results are determined by the white noise and the location of the 1/f corner frequency.

Figure 27 shows a circuit measuring current noise and the formula for calculating current noise.

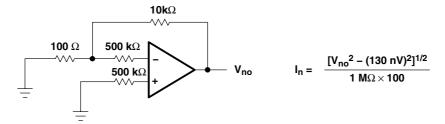


Figure 27. Current Noise Test Circuit and Formula

offset voltage adjustment

The input offset voltage and temperature coefficient of the OP27 are permanently trimmed to a low level at wafer testing. However, if further adjustment of V_{IO} is necessary, using a 10-k Ω nulling potentiometer as shown in Figure 28 does not degrade the temperature coefficient α_{VIO} . Trimming to a value other than zero creates an α_{VIO} of $V_{IO}/300~\mu V/^{\circ}C$. For example, if V_{IO} is adjusted to 300 μV , the change in α_{VIO} is 1 $\mu V/^{\circ}C$.

The adjustment range with a 10-k Ω potentiometer is approximately ± 2.5 mV. If a smaller adjustment range is needed, the sensitivity and resolution of the nulling can be improved by using a smaller potentiometer in conjunction with fixed resistors. The example in Figure 29 has an approximate null range of $\pm 200 \,\mu\text{V}$.

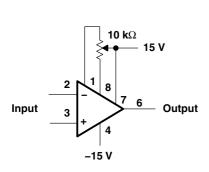


Figure 28. Standard Input Offset Voltage Adjustment

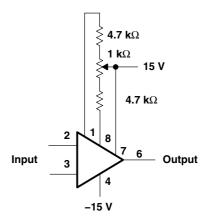


Figure 29. Input Offset Voltage Adjustment With Improved Sensitivity

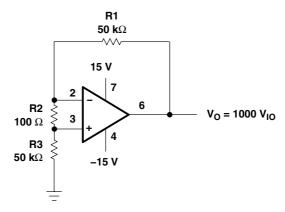
offset voltage and drift

Unless proper care is exercised, thermoelectric effects caused by temperature gradients across dissimilar metals at the contacts to the input terminals can exceed the inherent temperature coefficient ${}^{\infty}V_{IO}$ of the amplifier. Air currents should be minimized, package leads should be short, and the two input leads should be close together and at the same temperature.



offset voltage and drift (continued)

The circuit shown in Figure 30 measures offset voltage. This circuit can also be used as the burn-in configuration for the OP27 with the supply voltage increased to 20 V, R1 = R3 = 10 k Ω , R2 = 200 Ω , and A_{VD} = 100.



NOTE A: Resistors must have low thermoelectric potential.

Figure 30. Test Circuit for Offset Voltage and Offset Voltage Temperature Coefficient

unity gain buffer applications

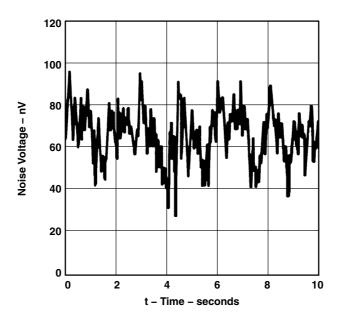
The resulting output waveform, when $R_f \le 100 \Omega$ and the input is driven with a fast large-signal pulse (>1 V), is shown in the pulsed-operation diagram in Figure 31.



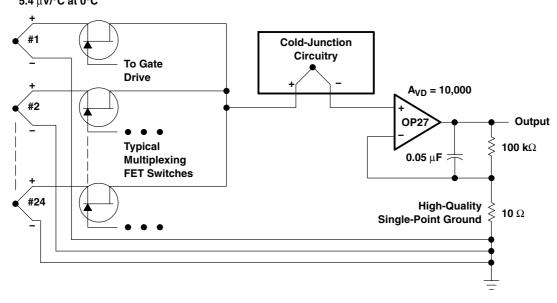
Figure 31. Pulsed Operation

During the initial (fast-feedthrough-like) portion of the output waveform, the input protection diodes effectively short the output to the input, and a current, limited only by the output short-circuit protection, is drawn by the signal generator. When $R_f \geq 500~\Omega$, the output is capable of handling the current requirements (load current $\leq\!20$ mA at 10 V), the amplifier stays in its active mode, and a smooth transition occurs. When $R_f > 2~k\Omega$, a pole is created with R_f and the amplifier's input capacitance, creating additional phase shift and reducing the phase margin. A small capacitor (20 pF to 50 pF) in parallel with R_f eliminates this problem.

unity gain buffer applications (continued)



Type S Thermocouples 5.4 μ V/°C at 0°C



NOTE A: If 24 channels are multiplexed per second and the output is required to settle to 0.1 % accuracy, the amplifier's bandwidth cannot be limited to less than 30 Hz. The peak-to-peak noise contribution of the OP27 will still be only 0.11 μV, which is equivalent to an error of only 0.02°C.

Figure 32. Low-Noise, Multiplexed Thermocouple Amplifier and 0.1-Hz to 10-Hz Peak-to-Peak Noise Voltage







25-Jan-2012

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/ Ball Finish	MSL Peak Temp ⁽³⁾	Samples (Requires Login)
JM38510/13506BPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	
M38510/13506BPA	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	
OP27AFKB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type	
OP27AJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	
OP27CJGB	ACTIVE	CDIP	JG	8	1	TBD	A42	N / A for Pkg Type	

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

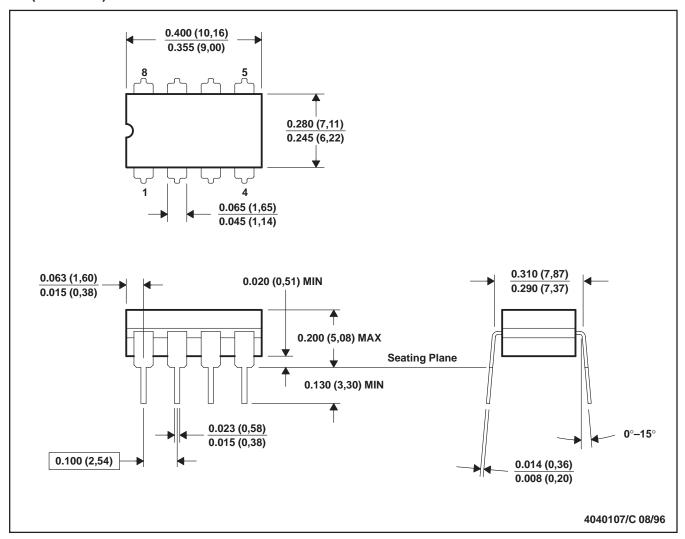
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE



NOTES: A. All linear dimensions are in inches (millimeters).

- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a ceramic lid using glass frit.
- D. Index point is provided on cap for terminal identification.
- E. Falls within MIL STD 1835 GDIP1-T8

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. This package can be hermetically sealed with a metal lid.
- D. Falls within JEDEC MS-004



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third-party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

TI products are not authorized for use in safety-critical applications (such as life support) where a failure of the TI product would reasonably be expected to cause severe personal injury or death, unless officers of the parties have executed an agreement specifically governing such use. Buyers represent that they have all necessary expertise in the safety and regulatory ramifications of their applications, and acknowledge and agree that they are solely responsible for all legal, regulatory and safety-related requirements concerning their products and any use of TI products in such safety-critical applications, notwithstanding any applications-related information or support that may be provided by TI. Further, Buyers must fully indemnify TI and its representatives against any damages arising out of the use of TI products in such safety-critical applications.

TI products are neither designed nor intended for use in military/aerospace applications or environments unless the TI products are specifically designated by TI as military-grade or "enhanced plastic." Only products designated by TI as military-grade meet military specifications. Buyers acknowledge and agree that any such use of TI products which TI has not designated as military-grade is solely at the Buyer's risk, and that they are solely responsible for compliance with all legal and regulatory requirements in connection with such use.

Applications

TI products are neither designed nor intended for use in automotive applications or environments unless the specific TI products are designated by TI as compliant with ISO/TS 16949 requirements. Buyers acknowledge and agree that, if they use any non-designated products in automotive applications, TI will not be responsible for any failure to meet such requirements.

Following are URLs where you can obtain information on other Texas Instruments products and application solutions:

Products

Wireless Connectivity

Audio www.ti.com/audio Automotive and Transportation www.ti.com/automotive **Amplifiers** amplifier.ti.com Communications and Telecom www.ti.com/communications dataconverter.ti.com Computers and Peripherals www.ti.com/computers **Data Converters DLP® Products** www.dlp.com Consumer Electronics www.ti.com/consumer-apps DSP dsp.ti.com **Energy and Lighting** www.ti.com/energy Clocks and Timers www.ti.com/clocks Industrial www.ti.com/industrial Interface interface.ti.com Medical www.ti.com/medical Logic logic.ti.com Security www.ti.com/security Power Mgmt www.ti.com/space-avionics-defense power.ti.com Space, Avionics and Defense Microcontrollers Video and Imaging microcontroller.ti.com www.ti.com/video www.ti-rfid.com **OMAP Mobile Processors** www.ti.com/omap

TI E2E Community Home Page

www.ti.com/wirelessconnectivity

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265 Copyright © 2012, Texas Instruments Incorporated

e2e.ti.com